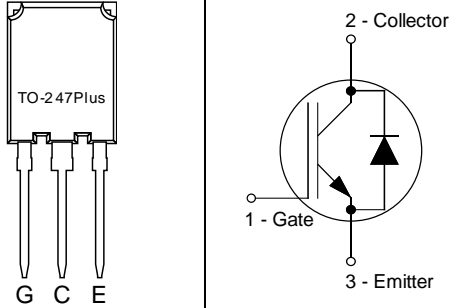


## 1200V 75A Trench and Field Stop IGBT

### Product Information

<b>Features</b> <ul style="list-style-type: none"> <li>◆ Advanced Field Stop technology</li> <li>◆ Low switching power loss</li> <li>◆ Low switching surge and noise</li> <li>◆ Low EMI</li> <li>◆ <math>T_{VJ}</math> 175°C</li> </ul> <b>Applications</b> <ul style="list-style-type: none"> <li>◆ Industrial UPS</li> <li>◆ Welding machine</li> <li>◆ Solar converters</li> <li>◆ Energy storage</li> <li>◆ EV Charger</li> </ul>	<b>Package Marking and Ordering Information</b>	
	<ul style="list-style-type: none"> <li>◆ Product Name: KJG75N120PL</li> <li>◆ Marking: KJG75N120PL</li> <li>◆ Package: TO-247 Plus-3L</li> <li>◆ Quantity: 300 pcs</li> </ul>	

### Maximum Rated Values ( $T_{VJ}=25^{\circ}\text{C}$ , unless otherwise specified)

Parameter	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CES}$	1200	V
Gate-Emitter Voltage	$V_{GE}$	$\pm 20$	V
Transient Gate-Emitter Voltage ( $t_p \leq 10 \mu\text{s}$ , $D < 0.010$ )		$\pm 30$	
DC Collector Current, $T_C=25^{\circ}\text{C}$ (Limited by $T_{VJ}$ max)	$I_C$	150	A
DC Collector Current, $T_C=100^{\circ}\text{C}$ (Limited by $T_{VJ}$ max)		75	
Pulsed collector current ( $T_p$ limited by $T_{VJ}$ max) <sup>[1]</sup>	$I_{Cpuls}$	300	
Diode Forward Current, $T_C=25^{\circ}\text{C}$ ( $T_p$ limited by $T_{VJ}$ max)	$I_F$	150	
Diode Forward Current, $T_C=100^{\circ}\text{C}$ ( $T_p$ limited by $T_{VJ}$ max)		75	
Turn-Off Safe Operating Area $V_{CE} \leq 1200 \text{ V}$ , $T_{VJ} \leq 175^{\circ}\text{C}$ , $t_p = 1 \mu\text{s}$	-	300	
IGBT Max. Power Dissipation	$P_{D\_IGBT}$	625	W
FWD Max. Power Dissipation	$P_{D\_FRD}$	350	
Operating Junction Temperature	$T_{VJ}$	-40 to 175	°C
Storage Temperature	$T_{stg}$	-55 to 150	

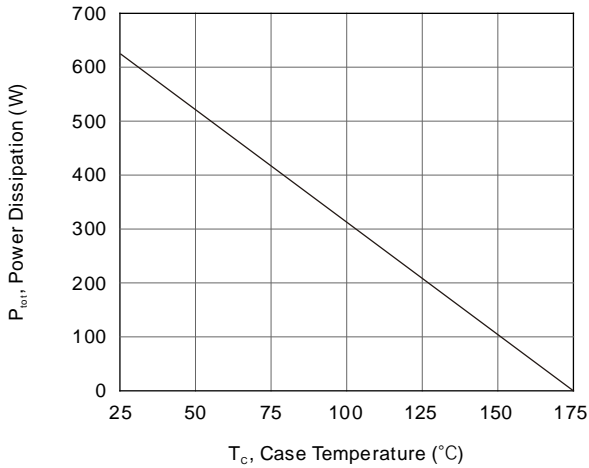
### Thermal Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-Ambient	$R_{\theta JA}$	-	-	50	°C/W
IGBT Thermal Resistance, Junction-Case	$R_{\theta JC}$	-	-	0.24	
Diode Thermal Resistance, Junction-Case	$R_{\theta JCD}$	-	-	0.43	

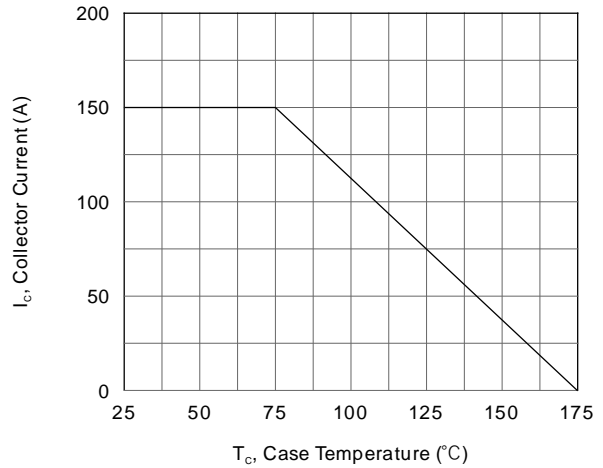
**Electrical Characteristics** ( $T_{VJ}=25^{\circ}\text{C}$ , unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Collector-Emitter Breakdown Voltage	$V_{(BR)CES}$	$V_{GE}=0\text{ V}$ , $I_C=0.50\text{ mA}$	1200	-	-	V
C-E Leakage Current	$I_{CES}$	$V_{CE}=1200\text{ V}$ , $V_{GE}=0\text{ V}$	-	-	200	$\mu\text{A}$
G-E Leakage Current	$I_{GES}$	$V_{CE}=0\text{ V}$ , $V_{GE}=\pm 30\text{ V}$	-	-	$\pm 200$	nA
G-E Threshold Voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$ , $I_C=2.6\text{ mA}$	5.0	5.8	6.6	V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE}=15\text{ V}$ , $I_C=75\text{ A}$ $T_{VJ}=25^{\circ}\text{C}$ $T_{VJ}=175^{\circ}\text{C}$	-	1.95 2.80	2.40 -	V
Diode Forward Voltage	$V_F$	$V_{GE}=0\text{ V}$ , $I_F=75\text{ A}$ $T_{VJ}=25^{\circ}\text{C}$ $T_{VJ}=175^{\circ}\text{C}$	-	2.2 1.8	3.0 -	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ies}$	$V_{CE}=25\text{ V}$ , $V_{GE}=0\text{ V}$ , $f=1\text{ MHz}$	-	19.5	-	pF
Output Capacitance	$C_{oes}$		-	240	-	
Reverse Transfer Capacitance	$C_{res}$		-	130	-	
Gate Charge	$Q_G$	$V_{CC}=960\text{ V}$ , $I_C=75\text{ A}$ , $V_{GE}=15\text{ V}$	-	590	-	nC
<b>IGBT Switching Characteristics</b>						
Turn-on Delay Time	$t_{d(on)}$	$T_{VJ}=25^{\circ}\text{C}$ , $V_{CC}=600\text{ V}$ , $I_C=75\text{ A}$ , $V_{GE}=15\text{ V}$ , $R_G=0.6\ \Omega$ , Inductive load	-	42	-	ns
Rise Time	$t_r$		-	146	-	
Turn-off Delay Time	$t_{d(off)}$		-	122	-	
Fall Time	$t_f$		-	105	-	
Turn-on Energy	$E_{on}$	Inductive load	-	4.0	-	mJ
Turn-off Energy	$E_{off}$		-	2.4	-	
Total Switching Energy	$E_{ts}$		-	6.4	-	
Turn-on Delay Time	$t_{d(on)}$	$T_{VJ}=175^{\circ}\text{C}$ , $V_{CC}=600\text{ V}$ , $I_C=75\text{ A}$ , $V_{GE}=15\text{ V}$ , $R_G=0.6\ \Omega$ , Inductive load	-	41	-	ns
Rise Time	$t_r$		-	138	-	
Turn-off Delay Time	$t_{d(off)}$		-	142	-	
Fall Time	$t_f$		-	132	-	
Turn-on Energy	$E_{on}$	Inductive load	-	3.6	-	mJ
Turn-off Energy	$E_{off}$		-	3.4	-	
Total Switching Energy	$E_{ts}$		-	7.0	-	
<b>Diode Characteristics</b>						
Diode Reverse Recovery Time	$t_{rr}$	$T_j=25^{\circ}\text{C}$ , $V_{CC}=600\text{ V}$ , $I_F=75\text{ A}$ , $di_F/dt=680\text{ A}/\mu\text{s}$	-	210	-	ns
Diode Reverse Recovery Charge	$Q_{rr}$		-	2.9	-	$\mu\text{C}$
Diode Peak Reverse Recovery Current	$I_{rrm}$		-	26	-	A
Diode Reverse Recovery Time	$t_{rr}$	$T_j=175^{\circ}\text{C}$ , $V_{CC}=600\text{ V}$ , $I_F=75\text{ A}$ , $di_F/dt=680\text{ A}/\mu\text{s}$	-	330	-	ns
Diode Reverse Recovery Charge	$Q_{rr}$		-	10.5	-	$\mu\text{C}$
Diode Peak Reverse Recovery Current	$I_{rrm}$		-	64	-	A

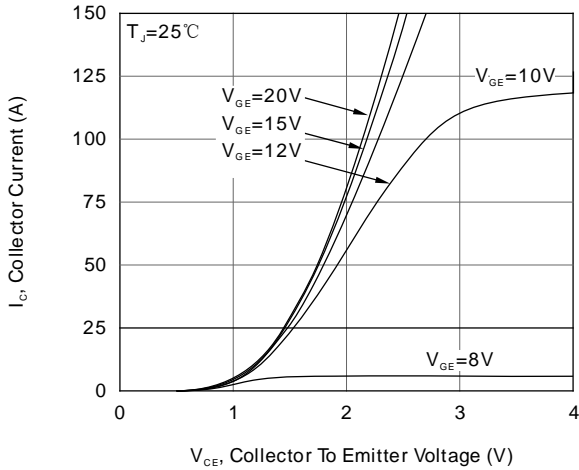
## Typical Electrical and Thermal Characteristics



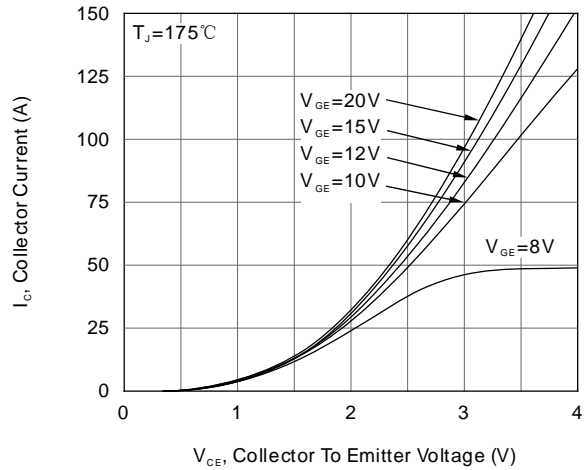
**Figure 1. Power dissipation vs. case temperature ( $T_{VJ} \leq 175^\circ\text{C}$ )**



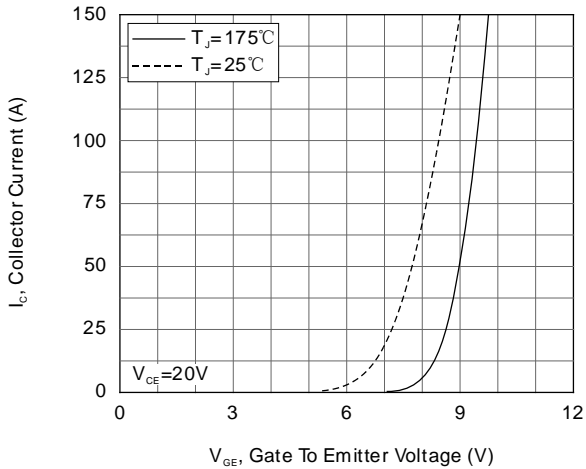
**Figure 2. Collector current vs. case temperature ( $V_{GE} \leq 15\text{V}, T_{VJ} \leq 175^\circ\text{C}$ )**



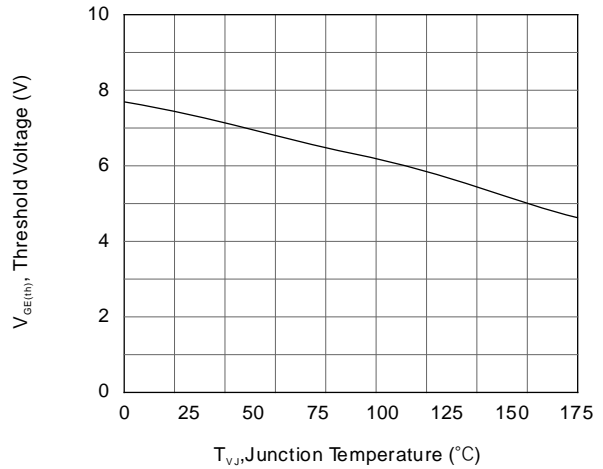
**Figure 3. Typical output characteristic ( $T_{VJ} = 25^\circ\text{C}$ )**



**Figure 4. Typical output characteristic ( $T_{VJ} = 175^\circ\text{C}$ )**

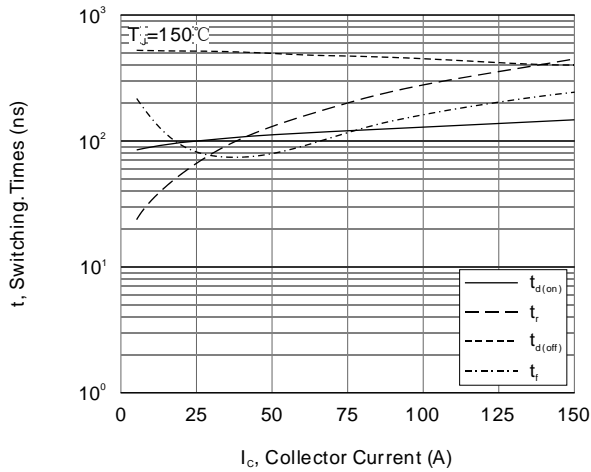


**Figure 5. Typical transfer characteristic ( $V_{CE} = 20\text{V}$ )**

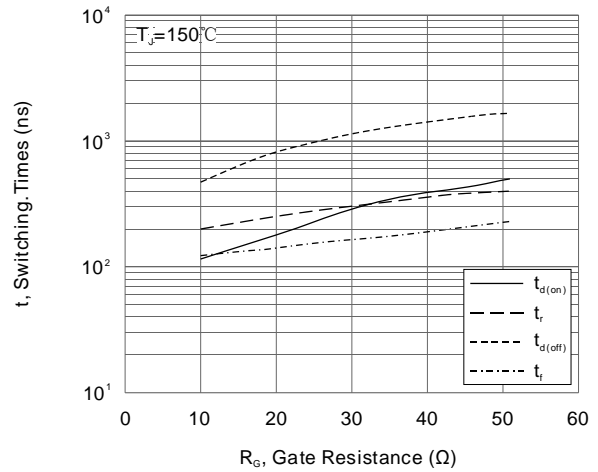


**Figure 6. Gate threshold voltage ( $I_c = 75\text{mA}, V_{CE} = 20\text{V}$ )**

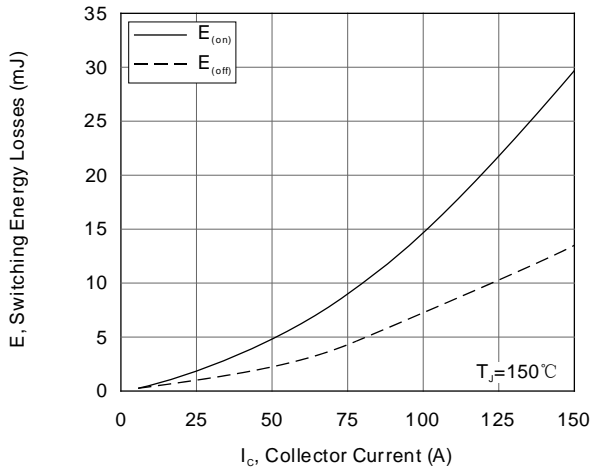
## Typical Electrical and Thermal Characteristics (cont.)



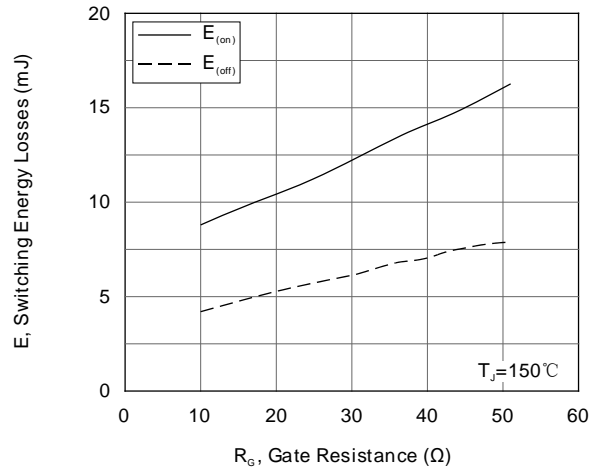
**Figure 7. Typical switching times vs. collector current**  
( $T_{VJ}=150^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_G=10\Omega$ )



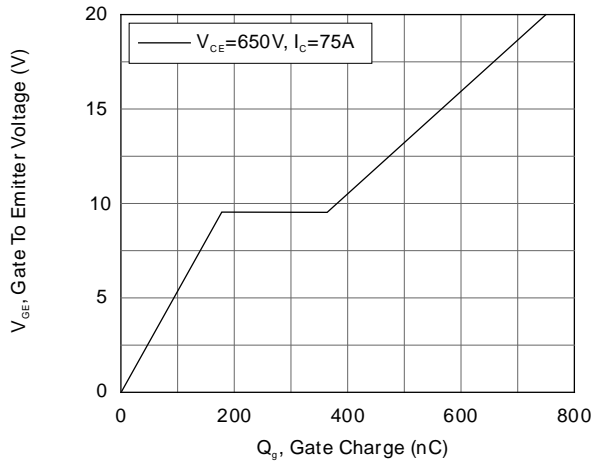
**Figure 8. Typical switching times vs. gate resistor**  
( $T_{VJ}=150^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=75\text{A}$ )



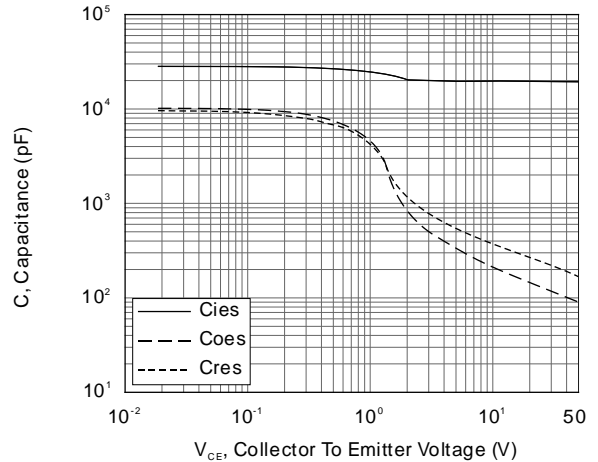
**Figure 9. Typical switching losses vs. Collector current**  
( $T_{VJ}=150^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_G=10\Omega$ )



**Figure 10. Typical switching losses vs. collector-emitter voltage**  
( $T_{VJ}=150^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_G=10\Omega$ )

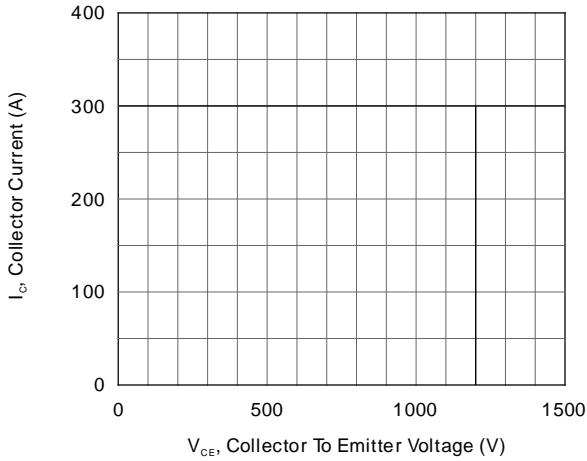


**Figure 11. Typical gate charge**  
( $T_{VJ}=25^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $I_C=75\text{A}$ )

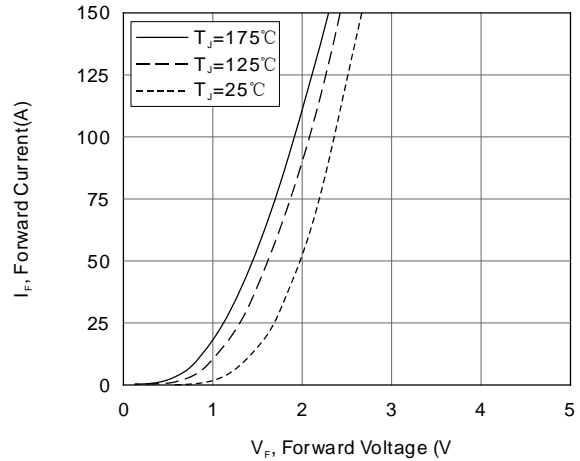


**Figure 12. Typical capacitance vs. collector-emitter voltage** ( $V_{GE}=0\text{V}$ ,  $f=1\text{MHz}$ )

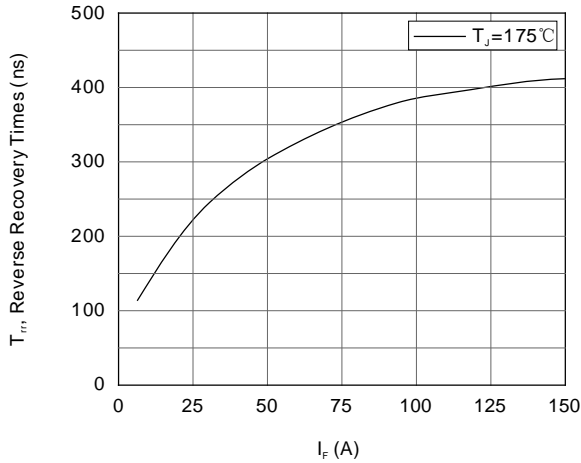
## Typical Electrical and Thermal Characteristics (cont.)



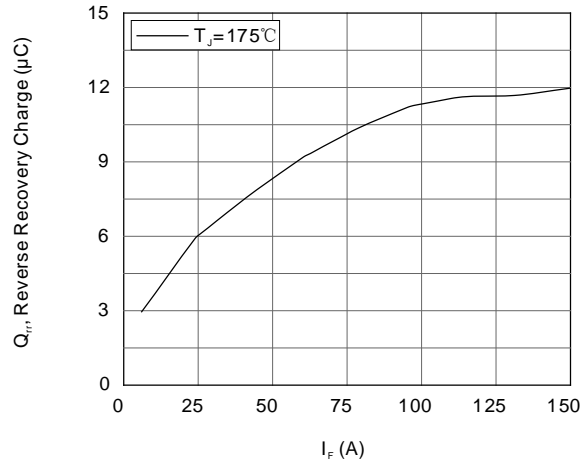
**Figure 13. Reverse biased safe operating area**  
( $T_{VJ}=175^{\circ}\text{C}$ ,  $V_{GE}=15/0\text{V}$ ,  $R_G=20\Omega$ )



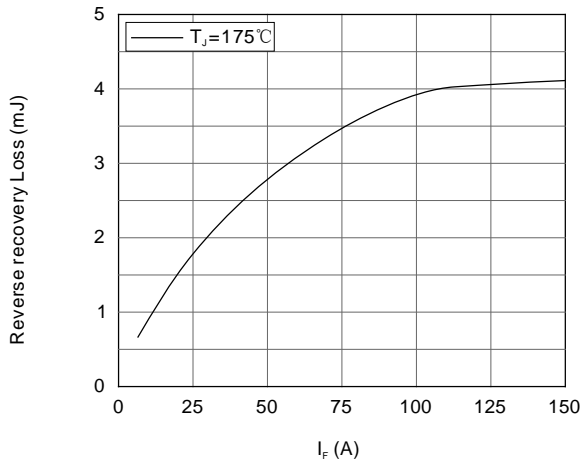
**Figure 14. Typical diode forward current vs. forward voltage**



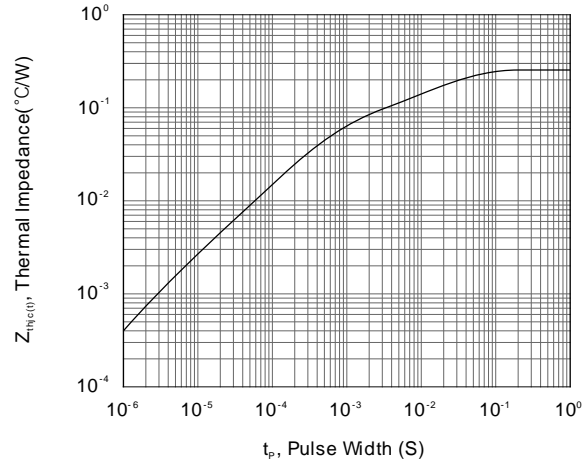
**Figure 15. Typical reverse recovery characteristics vs. forward current of diode**  
( $T_{VJ}=175^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_G=10\Omega$ )



**Figure 16. Typical reverse recovery characteristics vs. forward current of diode**  
( $T_{VJ}=175^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_G=10\Omega$ )



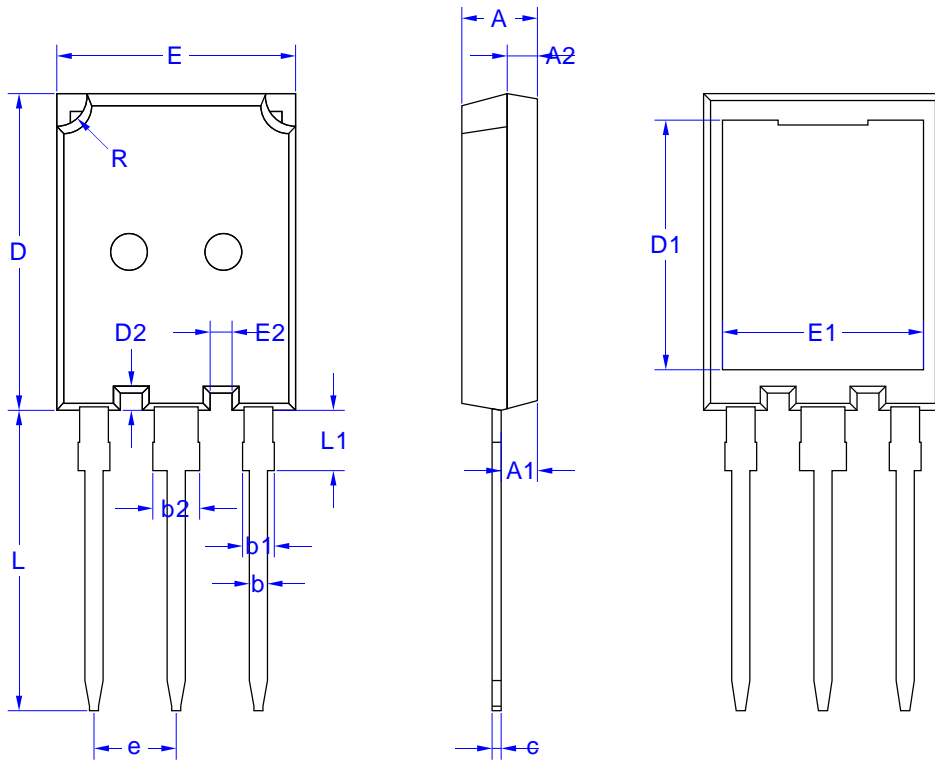
**Figure 17. Typical reverse recovery loss vs. forward current of diode**  
( $T_{VJ}=175^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_G=10\Omega$ )



**Figure 18. IGBT transient thermal impedance**  
( $D=tp/T$ )

## Package Mechanical Data

### TO-247 Plus-3L Package



Symbol	Dimensions in Millimeters		
	MIN.	NOM.	MAX.
A	4.80	5.00	5.20
A1	2.21	2.40	2.61
A2	1.85		2.15
b	1.07	1.20	1.33
b1	1.90		2.16
b2	2.90		3.20
c	0.52	0.60	0.68
D	20.70	21.00	21.30

Symbol	Dimensions in Millimeters		
	NOM.	NOM.	MAX.
D1	16.25	16.55	16.85
D2	0.53	0.68	0.83
E	15.50	15.80	16.10
E1	13.10	13.30	13.50
E2	1.30	1.45	1.60
e		5.44	
L	19.62	19.92	20.22
L1			4.30